

L Number	Hits	Search Text	DB	Time stamp
1	42	"5275330" and (metal\$6 or metalliz\$7) near layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 16:52
2	9	"4493856" and (metal\$6 or metalliz\$7) near layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 16:52
3	27173	(carrier or substrate or board or pcb or pwb) and (via or (via or (through or thru) adj hole)) and ((screen adj print\$4) or stencil\$4 or mask\$4 or screen) and (metal or metalliz\$6) near layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 16:57
4	3945	((carrier or substrate or board or pcb or pwb) and (via or (via or (through or thru) adj hole)) and ((screen adj print\$4) or stencil\$4 or mask\$4 or screen) and (metal or metalliz\$6) near layer ) and (via or (via or (through or thru) adj hole)) near (fill\$4 or plug\$6 or stop\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 16:58
5	67	((((carrier or substrate or board or pcb or pwb) and (via or (via or (through or thru) adj hole)) and ((screen adj print\$4) or stencil\$4 or mask\$4 or screen) and (metal or metalliz\$6) near layer ) and (via or (via or (through or thru) adj hole)) near (fill\$4 or plug\$6 or stop\$6)) and (via or (via or (through or thru) adj hole)) near thermal\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 17:14
6	1	"19842590"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 17:04
7	25	(((((carrier or substrate or board or pcb or pwb) and (via or (via or (through or thru) adj hole)) and ((screen adj print\$4) or stencil\$4 or mask\$4 or screen) and (metal or metalliz\$6) near layer ) and (via or (via or (through or thru) adj hole)) near (fill\$4 or plug\$6 or stop\$6)) and (via or (via or (through or thru) adj hole)) near thermal\$6) and (second\$4 or inner or interior or inside or outer or exterior or outside) near (layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 17:15